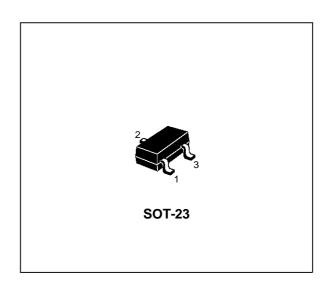
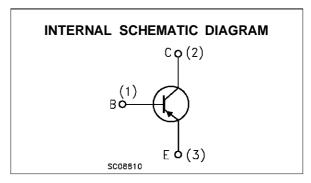


SMALL SIGNAL PNP TRANSISTOR

Type	Marking	
BSS63	Т3	

- SILICON EPITAXIAL PLANAR PNP TRANSISTORS
- MINIATURE PLASTIC PACKAGE FOR APPLICATION IN SURFACE MOUNTING CIRCUITS
- GENERAL PURPOSE LOW FREQUENCY APPLICATIONS
- NPN COMPLEMENT IS BSS64





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vсво	Collector-Base Voltage (V _{BE} = 0)	-110	V
V _{CEO}	Collector-Emitter Voltage (I _B = 0)	-100	V
V_{EBO}	Emitter-Base Voltage (I _C = 0)	-6	V
Ic	Collector Current	-0.1	Α
I _{CM}	Collector Peak Current	-0.2	Α
P _{tot}	Total Dissipation at T _c = 25 °C	200	mW
T _{stg}	Storage Temperature	-65 to 150	°C
Tj	Max. Operating Junction Temperature	150	°C

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THERMAL DATA

R _{thj-amb} •	Thermal Resistance	e Junction-Ambient	Max	620	°C/W
R _{thj-SR} •	Thermal Resistance	e Junction-Substrate	Max	500	°C/W

Mounted on a ceramic substrate area = 15 x 15 x 0.7 mm

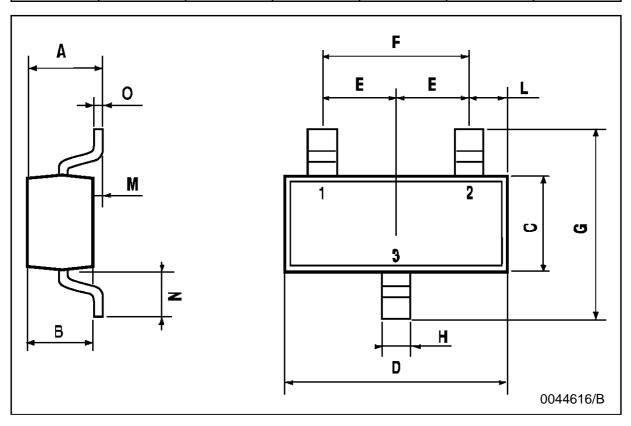
ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Ісво	Collector Cut-off Current (I _E = 0)	V _{CB} = -90 V V _{CB} = -90 V T _j = 150 °C			-100 -50	nA μA
I _{EBO}	Emitter Cut-off Current (I _C = 0)	V _{EB} = -5 V			-200	nA
V _{(BR)CBO} *	Collector-Base Breakdown Voltage (I _E = 0)	I _C = -10 μA	-110			V
V _{(BR)CEO*}	Collector-Emitter Breakdown Voltage (I _B = 0)	I _C = -10 mA	-100			V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage (I _C = 0)	Ι _Ε = -10 μΑ	-6			V
V _{CE(sat)*}	Collector-Emitter Saturation Voltage	$I_C = -25 \text{ mA}$ $I_B = -2.5 \text{ mA}$ $I_C = -75 \text{ mA}$ $I_B = -7.5 \text{ mA}$			-0.25 -0.9	V V
V _{BE(sat)} *	Emitter-Base Saturation Voltage	I _C = -25 mA I _B = -2.5 mA			-0.9	V
h _{FE} *	DC Current Gain	I _C = -10 mA	30 30			
f _T	Transition Frequency	$I_C = -25 \text{ mA } V_{CE} = -5 \text{ V } f = 100 \text{ MHz}$	50			MHz
ССВ	Collector Base Capacitance	$I_E = 0 \text{ mA}$ $V_{CB} = -10 \text{ V}$ $f = 1 \text{MHz}$		3		pF

^{*} Pulsed: Pulse duration = 300 μs, duty cycle ≤ 2 %

SOT-23 MECHANICAL DATA

DIM.	mm			mils		
DIWI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α	0.85		1.1	33.4		43.3
В	0.65		0.95	25.6		37.4
С	1.20		1.4	47.2		55.1
D	2.80		3	110.2		118
Е	0.95		1.05	37.4		41.3
F	1.9		2.05	74.8		80.7
G	2.1		2.5	82.6		98.4
Н	0.38		0.48	14.9		18.8
L	0.3		0.6	11.8		23.6
М	0		0.1	0		3.9
N	0.3		0.65	11.8		25.6
0	0.09		0.17	3.5		6.7



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